AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph starting on page 21, line 11 and ending on page 22, line 18 with the following:

After the laminating operation, in which the card body ~~16 has~~ 17 has been completed, in the latter a recess 12 must be made in the card body ~~16 for~~ 17 for receiving electronic components, such as for example the chip module 11. This usually takes place by a milling operation, in which, according to the invention, the covering layer 15, and possibly further layers arranged over the latter, is partially milled away from that side which is remote from the conductor tracks 2 located in the interior of the card ~~body 16~~ body 17, until the conductor track supporting layer 1 is reached, so that the recess 12 is produced. The depth of the recess 12 is dependent on the one hand on the thickness of the chip module 11, on the other hand it is clear from figure 4 that exposure of the connecting areas within the conductor track supporting layer 1 is necessary for the electrical bonding of the chip module 11 to these connecting areas 3 located within the card ~~body 16~~ body 17. The given thickness of the connecting areas 3 makes it possible for them to be exposed without any problem in the course of the milling operation, without the recess having to be made so deep that the conductor tracks 2 additionally arranged on the conductor track supporting layer 1 can possibly be contacted in any way and possibly be damaged, as is often the case with the conductor tracks known so far from the prior art. On the chip module 11, there are usually contact areas 13 which are connected to the connecting areas 3 by means of a conductive adhesive, which under some circumstances serves at the same time for fixing the chip module 11 within the recess 12 of the chip card 8.

Please amend page 23 as follows:

~~List of designations~~

~~1 conductor track supporting layer~~

~~2 conductor track~~

~~3 connecting area~~

~~4a indentation~~

~~4b indentation~~

~~4c indentation~~

~~5 screen printing paste~~

~~6 through-hole~~

~~7 opening~~

~~8 chip card~~

~~9 rear side~~

~~10 protective film~~

~~11 chip module~~

~~12 recess~~

~~13 contact area~~

~~14 covering layer~~

~~15 covering layer~~

~~16 card body~~

~~18 sublayer~~

~~19 sublayer~~

~~20 sublayer~~

~~21 through-hole~~